

VIGON® N 600

Water-based, pH-neutral defluxing agent for spray-in-air cleaning processes



VIGON® N 600 is an innovative defluxing product with a revolutionary pH-neutral formulation. The cleaning agent was developed to be used in spray-in-air inline and batch cleaning applications. Its excellent cleaning performance and ability to remove a wide range of flux residues from electronic assemblies under pH-neutral conditions is unprecedented. Due to its neutral pH-value, the cleaning agent also demonstrates a high level of material compatibility with sensitive metals and polymers.

Areas of application: PCB cleaning		Additional product information for this :
Low solid flux residues*	+	Technical Information 3: Material Compatibility overview MPC® Technology Sheet: Detailed information on the MPC® Technology
Water-soluble flux residues*	++	
Rosin-based flux residues*	++	
Solder paste (unsoldered)	+	

++ highly recommended, best results + recommended 0 possible (tested for standard batch cleaning equipment)
 - not recommended
 * Valid for all standard-, lead-free and lead-based solders

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ East-China, ⑤ South-China Cleaning Process Solutions under Production Floor Conditions



Advantages compared to other cleaners:

- Due to its neutral pH-value, VIGON® N 600 demonstrates an unprecedented level of material compatibility on sensitive materials such as aluminum, brass or nickel, plastics, labels and inks.
- Performs well at low application concentrations in specific processes
- Good results underneath low standoff components
- Due to the neutrality of the cleaning agent, the permission for sewage disposal is easier to obtain.

Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.

Process Steps	1. Cleaning	2. Rinsing	3. Drying
Spray-in-air (inline & batch)	VIGON® N 600	warm DI-water ¹	Hot air or circulating air
Dip tank (ideally with vacuum drying)	VIGON® N 600	warm DI-water ¹	Hot air, ideally with vacuum drying

¹ the DI-water should have a temperature of 30-40°C.

Technical Data		
Please note that the following information represents VIGON® N 600 at 15 % concentration.		
Density	(g/ccm) at 20°C/68°F	1.00
Surface tension	(mN/m) at 25°C/77°F	27.1
Boiling point	°C/°F	98 - 229°C / 208 - 444°F
Flash point	°C/°F	None until boiling
pH-value	10g/l H ₂ O	7.5 ²
Vapor pressure	(mbar) at 20°C/68°F	Approx. 20
Cleaning temperature	°C/°F	40 - 70°C / 104 - 158°F
Solubility in water		Soluble
Application concentration ¹ (inline)	Concentrate	10 - 15 %
Application concentration ¹ (batch)	Concentrate	15 - 20%
HMIS Rating	Health-Flammability-Reactivity	0 - 0 - 0

¹ VIGON® N 600 is recommended to be diluted in DI-water. ² +/-0.5

PRODUCT FEATURES



Extensively tested and suitable for cleaning of lead-free solder pastes



MPC® Technology ensures an extremely long bath life when used in a closed loop system



100% compliance with EU guidelines (RoHS 1 & 2, WEEE)



Product is free of any critical substances according to SIN & SVHC lists

Filter recommendation

- To take full advantage of the MPC® Technology and further expand the bath life of VIGON® N 600, filtration is recommended.
- For details, please request our "Filter Recommendation" sheet.

Environmental, health and safety regulations:

- VIGON® N 600 is water-based and biodegradable.
- VIGON® N 600 is formulated free of any halogenated compounds.
- Refer to the MSDS for specific handling precautions and instructions.

Availability/Storage:

- VIGON® N 600 is available as a concentrate in 1l bottles, 5l or 25l containers and 200l drums.
- Store VIGON® N 600 in the original container at a temperature between 5 - 30°C / 41 - 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Cleaning Standards

Electronic assemblies cleaned with VIGON® N 600 in a ZESTRON specified process meet the following industry standards:

- IPC-A-610 Visual cleanliness
- J-STD 001 Ionic and resin cleanliness
- IPC-TM 650 and DIN 32513 (surface resistance)
- J-STD 003 Solderability